A METHOD AND MACHINE FOR UNDERFILLING AN ASSEMBLY TO FORM A SEMICONDUCTOR PACKAGE

ABSTRACT OF THE DISCLOSURE

A method and machine (1) for underfilling an assembly (8) to form semiconductor package is disclosed. The machine (1) has conveying tracks (2) for continuously conveying the assembly (8) past zones. The assembly (8) has a flexible tape substrate (9) with a mounted inverted semiconductor die (10). The machine includes a preheating zone (3), a dispensing zone (4) for dispensing an underfill material onto the substrate (9) whilst heating the assembly (8) to allow the underfill to flow into a gap between the substrate (9) and semiconductor die (10). The machine (1) also has a postheating zone (5) for postheating the assembly (8) after dispensing to provide for a continuous flow of the underfill into the gap.

Figure 1 accompanies this abstract